

Microsemi Corporation: PCN18003

November 17, 2017

Product/Process Change Notification No: PCN18003

Change Classification: Major

Subject

IGLOO Devices in CS196 and CSG196 Packages Converting from Gold to Gold Flash Palladium Coated Copper (AuPCC) Wire

Description of Change

Qualification of Gold Flash Palladium Coated Copper (AuPCC) wire for IGLOO devices in CS196 and CSG196 packages was completed. See the [Appendix \(see page 2\)](#) for the complete list of devices.

Reason for Change

Conversion to AuPCC wire is aligned with the current industry trend. Our assembly vendors have extensive experience in copper bond wire assembly. Copper wire is used in high-volume production by our assembly vendors and it has demonstrated equal electrical and mechanical performance to gold wire. Products assembled with copper bond wire have no changes in their product moisture sensitivity level (MSL), product functionality, performance, quality, or reliability.

Products assembled with copper wire only use halogen-free materials. Contact Microsemi for details on the materials for copper wire assembly.

Application Impact

There is no impact on form, fit, function, or MSL rating of the device. The datasheet and package specifications remain the same.

Products Affected by this Change

See the [Appendix \(see page 2\)](#) for the complete list of devices.

Production Shipment Schedule

Microsemi may begin shipping the devices with AuPCC wire beginning February 1, 2018.

Microsemi reserves the right to continue the shipment of devices with Au wire following the change implementation date. Customers may receive a mix of pre-conversion (Au wire) and products with AuPCC wire interchangeably, following the change implementation date.

Qualification Data

The qualification report is available upon request.

Samples Availability

Please contact your local Microsemi representative for information.

Contact Information

If you have further questions about this subject, contact Microsemi's Technical Support at soc_tech@microsemi.com.

Regards,

Microsemi Corporation

Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

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Appendix

Table 1 • List of Affected Devices

Standard Part Number
AGL125V2-CS196
AGL125V2-CS196I
AGL125V2-CSG196
AGL125V2-CSG196I
AGL125V5-CS196
AGL125V5-CS196I
AGL125V5-CSG196
AGL125V5-CSG196I
AGL250V2-CS196
AGL250V2-CS196I
AGL250V2-CSG196
AGL250V2-CSG196I
AGL250V5-CS196
AGL250V5-CS196I
AGL250V5-CSG196
AGL250V5-CSG196I
AGL400V2-CS196
AGL400V2-CS196I
AGL400V2-CSG196
AGL400V2-CSG196I
AGL400V5-CS196
AGL400V5-CS196I
AGL400V5-CSG196
AGL400V5-CSG196I



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